2SC2404

Silicon NPN epitaxial planar type

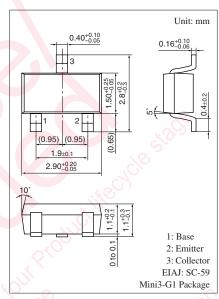
For high-frequency amplification

Features

- Optimum for RF amplification of FM/AM radios
- \bullet High transition frequency $f_{\rm T}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

			>	
Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	30	V	
Collector-emitter voltage (Base open)	V _{CEO}	20	v	
Emitter-base voltage (Collector open)	V _{EBO}	3	V	
Collector current	I _C	15	mA	
Collector power dissipation	P _C	150	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: U

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

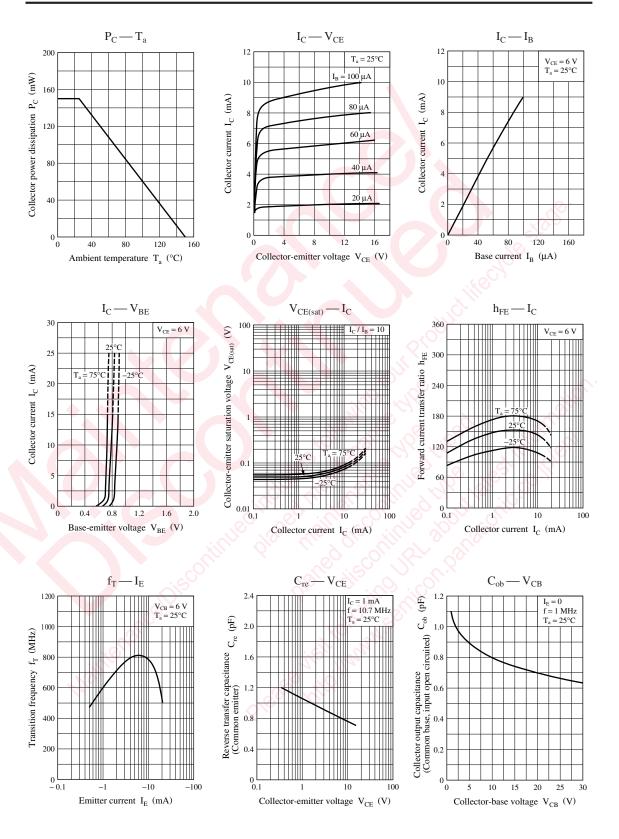
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	30	ŝ		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	3	^o		V
Base-emitter voltage	V _{BE}	$V_{CB} = 6 V, I_E = -1 mA$	$\sqrt{2}$	0.72		V
Forward current transfer ratio *	h _{FE}	$V_{CB} = 6 V, I_E = -1 mA$	65		260	_
Transition frequency	f _T	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$	450	650		MHz
Reverse transfer capacitance (Common emitter)	C _{re}	$V_{CB} = 6 V, I_E = -1 mA, f = 10.7 MHz$		0.8	1.0	pF
Power gain	G _P	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$		24		dB
Noise figure	NF	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$		3.3		dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

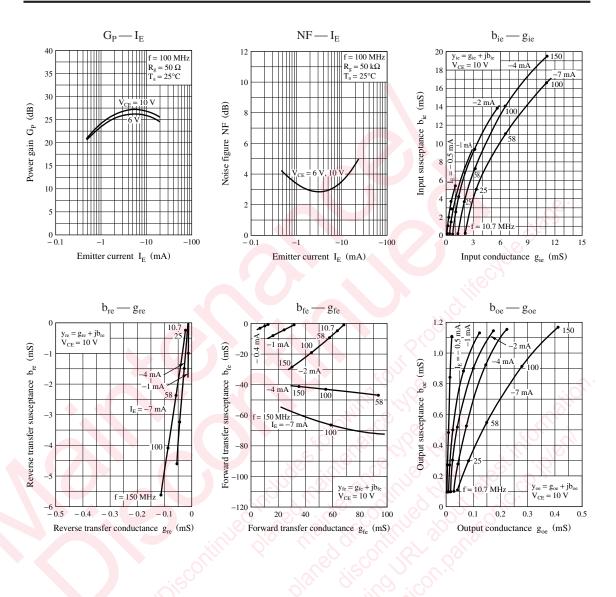
2. *: Rank classification

Rank	С	D
$h_{\rm FE}$	65 to 160	100 to 260

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